

ABSTRACT

There is disclosed a dual magnetron sputtering apparatus that is comprised of a balancing circuit connected to the output of an ac power source that supplies ac power to
5 at least two target materials such that the balancing circuit allows the power supply to deliver equal power to each target material. In those applications where there may be an erosion of one target material faster than the other, the balancing circuit allows the power supply to deliberately unbalance the power to at least one of the target materials to reduce power to the target to compensate for faster erosion of the target.